# Abstracts

## Three-dimensional, W-band circuits using Si micromachining

*R.M. Henderson, T.M. Weller and L.P.B. Katehi. "Three-dimensional, W-band circuits using Si micromachining." 1999 MTT-S International Microwave Symposium Digest 99.2 (1999 Vol. II [MWSYM]): 441-444 vol.2.*

This paper presents results from the development effort of Si micromachined three-dimensional high density circuits for W-band operation. Measurements of the performance of a power distribution network in a multilayer environment show that on-wafer packaging improves performance and allows for high density integration, small size, and considerably reduced cost.

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